

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

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Declarations authorised by

Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 May 2009 [Approved: 22 September 2023 13:38 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	0.3%	Nickel REACH Article 67 Exemption	7440-02-0	1%
			Gold	7440-57-5	11.5%
			Polydimethylsiloxane rubber	63394-02-5	25%
			Silicon	7440-21-3	62.5%
			Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
Die attach	Lead and Lead alloys	0.1%	Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
			Carbon black	1333-86-4	1%
			ALUMINUM(III) HYDROXIDE	21645-51-2	5%
			Phenol, polymer with formaldehyde	9003-35-4	10%
Encapsulation	EP (Epoxy resin)	67.8%	Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	12%
			Quartz sand	60676-86-0	72%
			Copper	7440-50-8	0.7%
Leadfinish	Tin plating	0.6%	Silver	7440-22-4	2.8%
			Tin	7440-31-5	96.5%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	31.2%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name
BxxC3200...7000_HF	Bridge Rectifier Single Inline